



## Material Content Data Sheet



<b>Sales Product Name</b>		IPL60R185C7		<b>Issued</b>		1. August 2018			
<b>MA#</b>		MA001501272							
<b>Package</b>		PG-VSON-4-1		<b>Weight*</b>		187.90 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.951	2.10	2.10	21028	21028	
leadframe	inorganic material	phosphorus	7723-14-0	0.020	0.01		108		
	non noble metal	zinc	7440-66-6	0.081	0.04		431		
	non noble metal	iron	7439-89-6	1.619	0.86		8614		
wire	non noble metal	copper	7440-50-8	65.718	34.98	35.89	349751	358904	
	non noble metal	copper	7440-50-8	0.968	0.51	0.51	5149	5149	
	encapsulation	organic material	carbon black	1333-86-4	0.219	0.12		1165	
plastics	plastics	epoxy resin	-	11.274	6.00		59999		
		inorganic material	silicondioxide	60676-86-0	97.961	52.13	58.25	521351	582515
leadfinish	non noble metal	tin	7440-31-5	2.397	1.28	1.28	12759	12759	
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1341	1341	
solder	non noble metal	tin	7440-31-5	0.069	0.04		366		
	noble metal	silver	7440-22-4	0.086	0.05		458		
	non noble metal	lead	7439-92-1	3.284	1.75	1.84	17480	18304	
*deviation	< 10%				Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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